

Karl Suss MJB3 Mask Aligner



The KARL SUSS MA 6 Mask Aligner is designed for small volume production or pilot production environment. It offers flexibility in the handling of irregularly shaped substrates of varying thickness, as well as standard size wafers up to 3 inches in diameter. Wafers and substrates up to 6 mm thickness may be processed. After passing the NCF safety exam, users can request training on this machine by sending an email to ncftech@uic.edu. Those not trained can request an NCF work service order by contacting the lab manager.

Location: cleanroom, photolithography bay

Training: 3 sessions (2 trainings and a checkout session)

Technical Specifications:

- Mask Holders: 2 and 3-inch
- Wafer Holders: 2 and 3-inch
- Lamp: 365nm i-line Hg arc lamp
- Power: 300 Watts (2 channels @ 15mW and 20mW per square cm)
- Exposure Mode: hard contact (nitrogen pressure under the substrate) and soft contact (vacuum under the substrate)
- Back Side Alignment: Infrared camera